



(0.80 mm) .0315"

QSE SERIES

HIGH-SPEED GROUND PLANE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QSE

Insulator Material: Liquid Crystal Polymer Terminal Material: Phosphor Bronze

Plating: Au or Sn over 50 μ" (1.27 μm) Ni **Current Rating:** Contacts: 2 A per pin

(2 pins powered) Ground Plane: 23 A per ground plane (1 ground plane powered)

Operating Temp Range:
-55 °C to +125 °C
Voltage Rating:
225 VAC (5 mm Stack Height)

Max Cycles: **RoHS Compliant:**

PROCESSING

Lead-Free Solderable:

SMT Lead Coplanarity: (0.10 mm) .004" max (020-060) Board Stacking:

For applications requiring more than two connectors per board contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- 15 mm, 22 mm and 30 mm stack height
- 30 µ" (0.76 µm) Gold (Specify -H plating for Data Rate cable mating applications.)
- · Edge Mount
- 56 (-DP), 80, 100 positions per row
- · Retention, Guide Posts and Friction Lock options.

Some lengths, styles and options are non-standard, non-returnable.

Board Mates:

Cable Mates:

EQCD, EQDF (See Also Available Note)

Standoffs:

QSE

POWER/SIGNAL **APPLICATION**



Compatible with UMPT/UMPS for flexible two-piece power/signal solutions

(0.89)

035

Integral metal plane for power or ground Blade & Beam Design HIGH-SPEED CHANNEL PERFORMANCE QSE-D/QTE-D QSE-DP/QTE-DP QTE-D/QSE-D or QTE-DP/QSE-DP @ 5 mm Mated Stack Height

channel.For full SI performance data visit Samtec.comor contact

01

Rating based on Samtec reference SIG@samtec.com

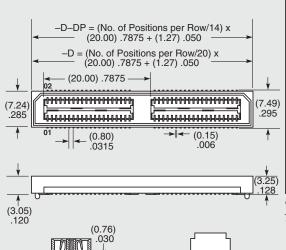
OTHER OPTION

-020, -040, -060(40 total pins per bank = -D)

PINS PER ROW

NO. OF PAIRS

-014, -028, -042(14 pairs per bank = -D-DP)



_F = Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails

PLATING

OPTION

= 10 µ" (0.25 µm) Gold on Signal Pins and Ground Plane, Matte Tin on tails

-C*= Electro-Polished Selective 50 μ" (1.27 μm) min Au over 150 μ" (3.81 µm) Ni on Signal

Pins in contact area. 10 μ" (0.25 μm) min Au over 50 μ" (1.27 μm) Ni on Ground Plane in contact area. Matte Tin over 50 μ" (1.27 µm) min Ni on all solder tails

C Plating passes
 year MFG testing

-GP = Guide Post = Single-Ended (-020 only)

D-DP = Differential Pair (-01 only)

–K (8.25 mm) .325' DIA Polyimide

Film Pick & Place Pad –TR

= Tape & Reel Packaging

Latching Option (N/A on –042 & -060 positions)

QTE LEAD STYLE	MATED HEIGHT WITH QSE*
-01	(5.00) .197
-02	(8.00) .315
-03	(11.00) .433
-04	(16.00) .630
-05	(19.00) .748
-07	(25.00) .984
-09	(14.00) .551

Processing conditions will affect mated height. See SO Series for board space tolerances

(0.64)

.025

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